Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Canceled)

2. (Currently amended) A glass ceramic sintered body according to claim [[1]] 8, wherein the flexural strength is not smaller than 150 MPa.

3. (Currently amended) A glass ceramic sintered body according to claim [[1]] 8, ~~wherein the content of~~ comprising PbO not larger than 0.1 mass % and ~~the content of~~ an alkali metal oxide ~~are~~ not larger than 0.1 mass %~~, respectively~~.

4. (Currently amended) A glass ceramic sintered body according to claim [[1]] 8, further ~~containing~~ comprising at least one of those selected from the group consisting of alumina, spinel, mullite, anorthite, slawsonite, celsian and ~~zirconir~~ zirconia, as a crystal phase.

5. (Canceled)

6. (Currently amended) A glass ceramic sintered body according to claim [[5]] 8, ~~containing~~ comprising a cordierite crystal phase in an amount of not smaller than 20 mass % and having a thermal expansion coefficient at 40 to 400°C of not larger than 4.5×10^{-6}/°C.

7. (Original) A glass ceramic sintered body according to claim 6, by using, as said filler powder, at least one inorganic powder for adjusting properties selected

from the group consisting of mullite, anorthite, slawsonite, celsian and quartz glass, and further using a cordierite powder.

8. (Currently amended) A glass ceramic sintered body ~~according to claim 5~~ comprising gahnite and cordierite as crystal phases, having a thermal expansion coefficient at 40 to 400°C of not larger than 5×10^{-6}/°C, a dielectric constant of not larger than 7 and a Young's modulus of not larger than 150 GPa, obtained by firing a mixed powder of a glass powder having the following composition:

SiO_2: 30 to 55 mass %

Al_2O_3: 15 to 40 mass %

MgO: 3 to 25 mass %

ZnO: 2 to 15 mass %

B_2O_3: 2 to 15 mass %

and a filler powder, wherein the glass ceramic sintered body further comprises ~~having~~ a CaO-containing glass phase.

9. (Currently amended) A glass ceramic sintered body according to claim 8, further ~~containing~~ comprising alumina as a crystal phase.

10. (Original) A glass ceramic sintered body according to claim 9, wherein the flexural strength is not smaller than 200 MPa, and a reduction in the weight of when immersed in a 1-mass % HF aqueous solution for one minute is not larger than 3 $\mu g/mm^2$.

11. (Original) A glass ceramic sintered body according to claim 10, wherein a CaO-releasing Ca compound powder, a cordierite powder and an alumina powder are used as said filler powders.

12. (Currently amended) A glass ceramic sintered body according to claim [[5]] 8 ~~wherein the~~ comprising cordierite, enstatite and/or forsterite ~~are contained~~ as crystal phases, the content of the cordierite is not smaller than 20 mass %, and the total content of the cordierite, enstatite and/or forsterite is not smaller than 40 mass %.

13. (Currently amended) A glass ceramic sintered body according to claim 12, wherein the flexural strength is not smaller than 200 MPa, and the cordierite ~~powder~~, enstatite ~~powder~~ and/or forsterite ~~powder~~ are used as said filler powders.

14-23. (Canceled)

24. (Currently amended) A wiring board having wiring layers of a low-resistance metal arranged on the front surface and/or inside of an insulating substrate made of a glass ceramic sintered body of claim [[1]] 8.

25. (Original) A wiring board according to claim 24, wherein a semiconductor device comprising chiefly silicon is arranged on the surface of said insulating substrate.

26. (Original) A wiring board according to claim 25, wherein a recessed portion is formed in the surface of said insulating substrate, and a semiconductor device comprising chiefly silicon is arranged in said recessed portion.

27. (Original) A mounted structure of a wiring board obtained by mounting a wiring board of claim 24 on the surface of a printed wiring board that has an insulating substrate containing an organic resin.